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INFORMATION DISCLOSURE STATEMENT BY APPLICANT (use as many sheets as necessary)		Complete if Known			
		Application Number	09/922,973 - 1445		
		Filing Date	August 6, 2001		
		First Named Inventor	Theodore M. Bloomstein et al		
		Art Unit	4752 1756		
		Examiner Name	Not Yet Assigned SAGAR		
Sheet	1	of	2	Attorney Docket Number	101328-160

U.S. PATENT DOCUMENTS					
Examiner Initials*	Cite No. ¹	Document Number Number-Kind Code ² (if known)	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
W	A	4,575,330	03/11/1986	Hull	425/174

FOREIGN PATENT DOCUMENTS						
Examiner Initials*	Cite No. 1	Foreign Patent Document	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear	T
		Country Code ³ -Number ⁴ -Kind Code ⁵ (if known)				

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OTHER PRIOR ART -- NON PATENT LITERATURE DOCUMENTS						
Examiner Initials	Cite No. ¹	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc), date, page(s), volume-issue number(s), publisher, city and/or country where published				T ²
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Sheet	2	of	2
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Application Number	09/922,973 - 1445
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First Named Inventor	Theodore M. Bloomstein et al
Group Art Unit	1752 → 1757
Examiner Name	Not Yet Assigned <i>SACENT</i>
Attorney Docket Number	101328-160

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Examiner Signature	Date Considered	
	7/1/03.	

*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

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